ABSTRACT

A film carrier tape provides reduced occurrence of lead bending during the making process, and allows a chip-size package to be made with high reliability, while increasing yield. The extremities of TAB leads (54a, 54b) are not connected to a frame (59), but are formed as free ends from the time of formation of the pattern, and are not subject to any process at all until the final bonding process. On the other hand, a plurality of link portions (57a to 57j) are provided within the mounting area of a semiconductor chip, linking many of leads within the mounting area of an IC chip, and through these link portions connecting them to a frame.